



Receipt
#8/B
PATENT
5298-02502/PM98019
OCT 18 2002
TECHNOLOGY CENTER 2800
RECEIVED
th

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Sethuraman et al.

Serial No. 09/779,123

Filed: February 07, 2001

For: A PLANARIZED SEMICONDUCTOR
INTERCONNECT TOPOGRAPHY
AND METHOD FOR POLISHING A
METAL LAYER TO FORM
INTERCONNECT

Group Art Unit: 2823

Examiner: Lee, H.

Atty. Dkt. No. 5298-02502

I hereby certify that this correspondence is being deposited
with the U.S. Postal Service with sufficient postage as First Class
Mail in an envelope addressed to: **Box: Non-Fee Amendment,**
Commissioner for Patents, Washington, D.C. 20231, on the date
indicated below:

October 3, 2002

Date

Kevin L. Daffer

AMENDMENT; RESPONSE TO OFFICE ACTION MAILED JULY 3, 2002

Commissioner for Patents
Washington, D.C. 20231

Dear Sir/ Madam:

This paper is submitted in response to the Office Action mailed July 3, 2002 to further highlight reasons why the application is in condition for allowance.

Please amend the case as follows:

In the Claims:

Please replace claims 1-3, 10-11, and 17 with the amended claims below. A "marked-up" version of each amendment is included in **Attachment A**.